SDLS004

D2633 JANUARY 1981 - REVISED MARCH 1988

- Parallel Register Inputs ('LS592)
- Parallel 3-State I/O: Register Inputs/ Counter Outputs ('LS593)
- Counter has Direct Overriding Load and Clear
- Accurate Counter Frequency: DC to 20 MHz

description

The 'LS592 comes in a 16-pin package and consists of a parallel input, 8-bit storage register feeding an 8-bit binary counter. Both the register and the counter have individual positive-edge-triggered clocks. In addition, the counter has direct load and clear functions. A low-going $\overline{\text{RCO}}$ pulse will be obtained when the counter reaches the hex word FF. Expansion is easily accomplished for two stages by connecting $\overline{\text{RCO}}$ of the first stage to $\overline{\text{CCKEN}}$ of the second stage. Cascading for larger count chains can be accomplished by connecting $\overline{\text{RCO}}$ of each stage to CCK of the following stage.

The 'LS593 comes in a 20-pin package and has all the features of the 'LS592 plus 3-state I/O, which provides parallel counter outputs. The tables below show the operation of the enable (CCKEN, $\overline{\text{CCKEN}}$) inputs. A register clock enable ($\overline{\text{RCKEN}}$) is also provided.

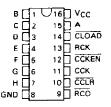
OUTPUT ENABLE CONTROL ('593 ONLY)

	G	G	A/Q _A thru H/Q _H
ı	L	L	input mode
	L	H	input mode
ı	Н	L	output mode
l	н	Н	input mode

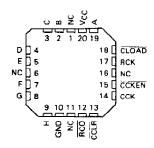
COUNTER CLOCK ENABLE CONTROL

CCKEN	CCKEN	EFFECT ON CCK
Ł	L	Enable
L	Н	Disable
н	L	Enable
Н	н	Enable

SN54LS592 . . . J OR W PACKAGE SN74LS592 . . . N PACKAGE (TOP VIEW)

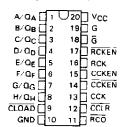


SN54LS592 . . . FK PACKAGE (TOP VIEW)

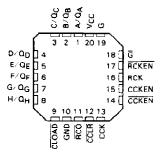


NC - No internal connection

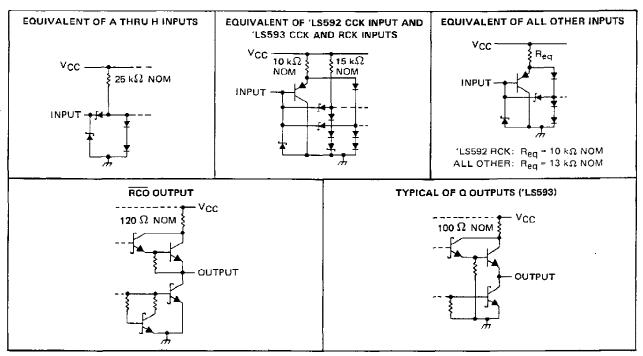
SN54LS593 . . . J OR W PACKAGE SN74LS593 . . . DW OR N PACKAGE (TOP VIEW)



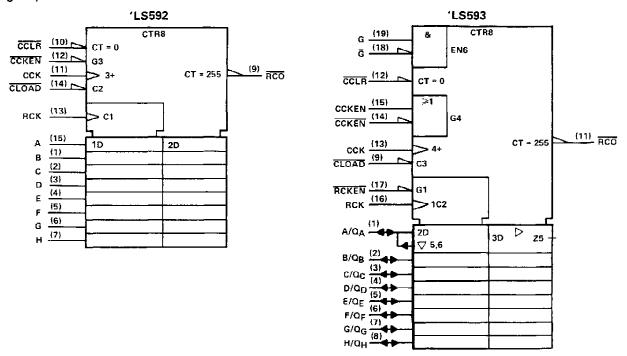
SN54LS593 . . . FK PACKAGE (TOP VIEW)



schematics of inputs and outputs

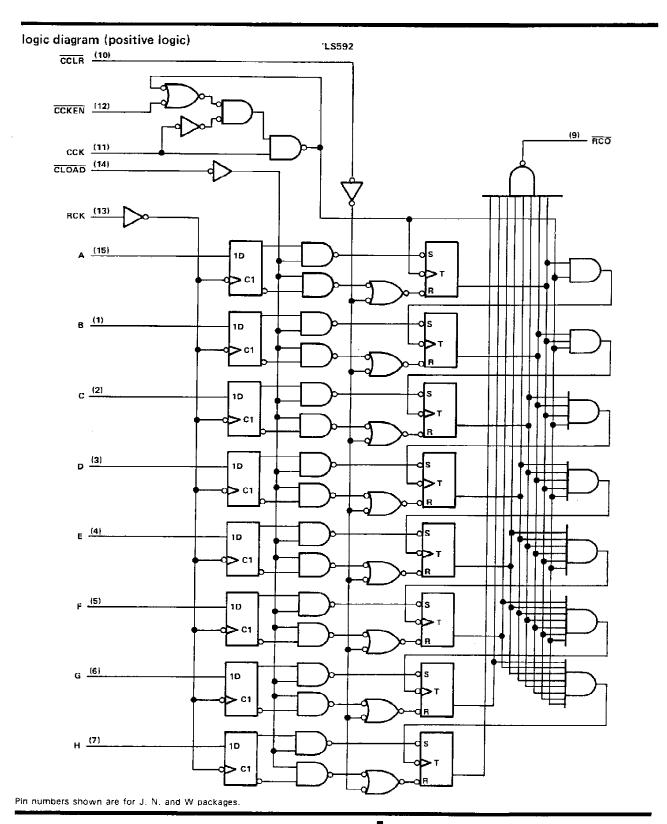


logic symbols†

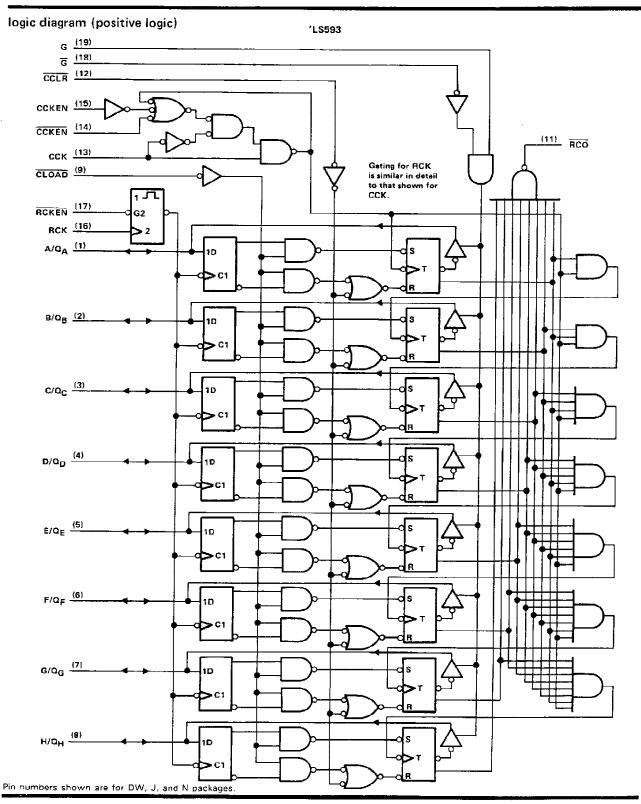


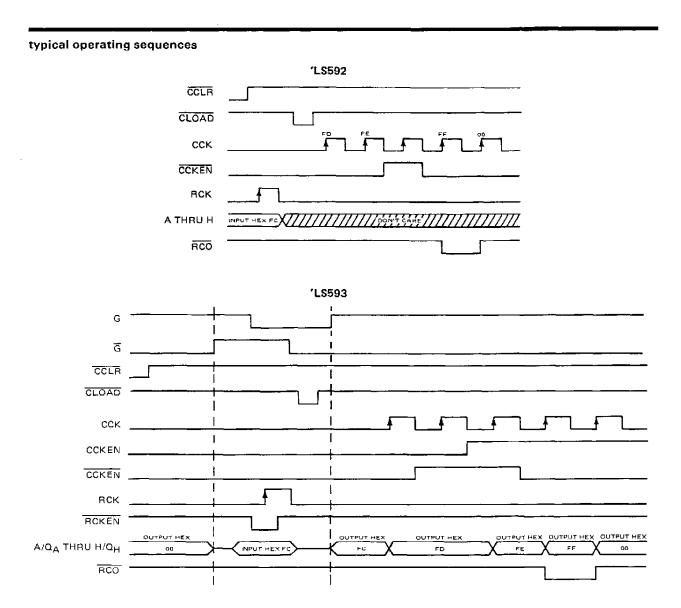
[†]These symbols are in accordance with ANSI/IEEE Std. 91-1984 and IEC Publication 617-12. Pin numbers shown are for DW, J, N, and W packages.





SN54LS593, SN74LS593 8-BIT BINARY COUNTERS WITH INPUT REGISTERS





absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage, VCC (see Note 1) 7 V	
Input voltage (excluding I/O ports)	
Off-state output voltage (including I/O ports)	
Operating free-air temperature range: SN54LS592, SN54LS593 55°C to 125°C	
SN74LS592, SN74LS593 0°C to 70°C	
Storage temperature range — 65°C to 150°C	

NOTE 1: Voltage values are with respect to the network ground terminal.

recommended operating conditions

	-	······································	SN54LS'		SN74LS'			UNIT	
			MIN	NOM	MAX	MIN	NOM	MAX	UNII
Vcc	Supply voltage		4.5	5	5.5	4.75	5	5.25	V
VIH	High-level input voltage		2			2			V
v_{IL}	Low-level input voltage				0.7			8.0	V
lan	High level entent en-	RCO			- 1			- 1	
Іон	High-level output current	Q 'LS593 only			- 1			- 2.6	mΑ
101	Law-level output current	RCO			8			16	
'OL	Low-level bulbut current	Q 'LS593 only			12			24	mA
fcck	Counter clock frequency		0		20	0		20	MHz
^t w (CCK)	Duration of counter clock p	ulse	25			25			ns
tw (CCLR)	Duration of counter clear pu	ilse	20	•		2D			ns
tw (RCK)	Duration of register clock pe	ılse	20			20			ns
tw (CLOAD	Duration of counter load pu	Ise	40			40			ns
t _{su}	Register enable setup time	RCKEN low to RCK 1 , 'LS593	20			20			ns
	Counter enable setup time	CCKEN low, 'LS592	30			30			
t _{Su}	before CCK †	CCKEN low or CCKEN high, 'LS593				30			ns
		CCLR inactive before CCK 1	20			20			
+	Setup time	CLOAD inactive before CCK †	20			20			
^t su	octop time	RCK # before CLOAD # (see Note 2)				30			ns
		Data A thru H before RCK †	20			20			
th	Hold time	Data A thru H after RCK †	0			0			
*11	TOTAL STITLE	All others	0			0			ns
T_A	Operating free-air temperatu	re	- 55		125	0		70	°C

NOTE 2: This time insures the data saved by RCK ↑ will also be loaded into the counter.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS			SN54LS'			SN74LS'		
					TYP‡	MAX	MIN	TYP [‡]	MAX	UNIT
Vik						- 1.5			- 1.5	٧
	'LS593 Q	V _{CC} = MIN, V _{IH} = 2 V,	I _{OH} = -1 mA	2.4	3.2					
Vон		V _{II} = MAX	I _{OH} = -2.6 mA	<u> </u>			2.4	3.1		٧
	RCO	AIT - MAY	I _{OH} = -1 mA	2.4	3.2		2.4	3.2		
	'LS593 Q		l _{OL} = 12 mA		0.25	0.4		0.25	0.4	
VOL	20000 0	V_{CC} - MIN, V_{IH} = 2 V,	I _{OL} = 24 mA			_		0.35	0.5	v
TUL	RCO	V _{IL} = MAX	IOL = 8 mA		0.25	0.4		0.25	0.4	
			IOL = 16 mA					0.35	0.5	
^I OZH	'LS593 Q	VCC = MAX, VIH = 2 V.	V _{IL} = MAX,			20			20	μА
'02H	20000 (2	V _O = 2.7 V								
OZL	′LS593 Q	V _{CC} = MAX, V _{IH} - 2 V,	$V_{IL} = MAX$			-0.4			-0.4	mΑ
·UZL	10000 0	V _O = 0.4 V				• • • • • • • • • • • • • • • • • • • •				
11	'LS593 Q	V _{CC} - MAX	V _I = 5.5 V			0.1			0.1	mΑ
"I	Others		V _I = 7 V	0.1		0.1			0.1	<u> </u>
^t iH		$V_{CC} = MAX$, $V_{I} = 2.7 V$				20			20	μА
	CCK					-0.8			-0.8	
	RCK LS592					-0.2			-0.2	
IIL	'LS593	'LS593 $V_{CC} = MAX$, $V_{I} = 0.4 V$				-0.B			- O.8	mA
	A thru H				-0.4			-0.4		
	Others					-0.2			-0.2	
los⁵	'LS593 Q	$V_{CC} = MAX, V_{C} = 0 V$	Y Vo = 0.V			- 130	- 30		- 130	mA
.03	RCO	100 111111		- 20		- 100	- 20		- 100	
	'LS592 CCH				40	60		40	60	
	ICCL	V _{CC} = MAX,			40	60		40	60	
ICC	<u> Іссн</u>	All possible inputs grounded,			47	70		47	70	mΑ
	'LS593 I _{CCL}	All outputs open		53	80		53	80		
	l (ccz				57	85	l	57	85	

Teor conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

 $^{^{\}ddagger}$ All typical values are at V_{CC} = 5 V, T_A = 25 °C.

Not more than one output should be shorted at a time and the duration of the short-circuit should not exceed one second.

switching characteristics, $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ}\text{C}$, (see note 3)

•	FROM	ROM TO				'LS592			'LS593		
PARAMETER	(INPUT) (OUTPUT)		TEST COND	MIN	TYP	MAX	MIN	TYP	MAX	UNIT	
fmax	ССК	RCO	$R_L = 1 k\Omega$,	CL = 30 pF	20	35		20	35		MHz
¹₽LH	CCK1	Q							14	21	ns
tPHL	CCK1	Q							26	39	nş
īРLН	CLOAD +	Q							34	51	ns
tpHL	CLOAD +	Ω							28	42	ns
tPHL	CCLR +	۵	R _L = 667 Ω,	Cլ = 45 pF					25	38	ns
^t PZH	G t	Q	1						31	47	ns
[†] PZL	G t	Q							27	40	ns
^t PZH	G↓	Q							29	45	ns
tPZL.	G ↓	a	1						31	47	ns
tPHZ	G l	a							33	50	ns
^t PL Z	G↓	a	, aa	0 5 5					35	52	ns
tpH2	<u>G</u> 1	۵	RL = 667 Ω,	C[=5p⊦					26	39	ns
^t PLZ	Ğt	Q	1						28	42	ns
[†] PLH	CCK t	RÇO				15	23		14	21	ns
[†] PHL	CCK 1	RCO	1			20	30		20	30	ns
tPLH	CLOAD +	ACO	R _L = 1 kΩ,	$C_L = 30 pF$		31	47		31	47	ns
tpHL.	CLOAD :	RCO				27	41		27	41	ns
^t PLH	CCLR +	ACO				30	45		30	45	ns
tPLH	RCK 1	RCO	ŘL = 1 kΩ;	C _L = 30 pF		35	53		42	63	ns
tPHL.	RCK †	RCO	CLOAD = L			30	45		33	50	ns

NOTE 3: Load circuits and voltage waveforms are shown in Section 1.

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PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	e Eco Plan ⁽²⁾ I	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
5962-87621012A	ACTIVE	LCCC	FK	20	1	TBD	Call TI	Level-NC-NC-NC
5962-8762101EA	ACTIVE	CDIP	J	16	1	TBD	Call TI	Level-NC-NC-NC
5962-8762101EA	ACTIVE	CDIP	J	16	1	TBD	Call TI	Level-NC-NC-NC
5962-8762101FA	ACTIVE	CFP	W	16	1	TBD	Call TI	Level-NC-NC-NC
5962-8762101FA	ACTIVE	CFP	W	16	1	TBD	Call TI	Level-NC-NC-NC
SN54LS592J	ACTIVE	CDIP	J	16	1	TBD	Call TI	Level-NC-NC-NC
SN54LS592J	ACTIVE	CDIP	J	16	1	TBD	Call TI	Level-NC-NC-NC
SN54LS593J	ACTIVE	CDIP	J	20	1	TBD	Call TI	Level-NC-NC-NC
SN54LS593J	ACTIVE	CDIP	J	20	1	TBD	Call TI	Level-NC-NC-NC
SN74LS592D	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1YEAR
SN74LS592D	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1YEAR
SN74LS592DE4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1YEAR
SN74LS592DE4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1YEAR
SN74LS592DR	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1YEAR
SN74LS592DR	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1YEAR
SN74LS592DRE4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1YEAR
SN74LS592DRE4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1YEAR
SN74LS592N	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	Level-NC-NC-NC
SN74LS592N	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	Level-NC-NC-NC
SN74LS592N3	OBSOLETE	PDIP	N	16		TBD	Call TI	Call TI
SN74LS592N3	OBSOLETE	PDIP	N	16		TBD	Call TI	Call TI
SN74LS592NE4	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	Level-NC-NC-NC
SN74LS592NE4	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	Level-NC-NC-NC
SN74LS592NSR	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS592NSR	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS592NSRE4	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS592NSRE4	ACTIVE	so	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS593DW	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS593DW	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM





26-Sep-2005

SN74LS593DWE4		Type	Drawing		Qty	e Eco Plan ⁽²⁾		MSL Peak Temp ⁽³⁾
	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS593DWE4	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS593DWR	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS593DWR	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS593DWRE4	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS593DWRE4	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS593N	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	Level-NC-NC-NC
SN74LS593N	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	Level-NC-NC-NC
SN74LS593N3	OBSOLETE	PDIP	N	20		TBD	Call TI	Call TI
SN74LS593N3	OBSOLETE	PDIP	N	20		TBD	Call TI	Call TI
SN74LS593NE4	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	Level-NC-NC-NC
SN74LS593NE4	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	Level-NC-NC-NC
SN74LS593NSR	ACTIVE	SO	NS	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS593NSR	ACTIVE	SO	NS	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS593NSRE4	ACTIVE	SO	NS	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS593NSRE4	ACTIVE	SO	NS	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SNJ54LS592FK	ACTIVE	LCCC	FK	20	1	TBD	Call TI	Level-NC-NC-NC
SNJ54LS592FK	ACTIVE	LCCC	FK	20	1	TBD	Call TI	Level-NC-NC-NC
SNJ54LS592J	ACTIVE	CDIP	J	16	1	TBD	Call TI	Level-NC-NC-NC
SNJ54LS592J	ACTIVE	CDIP	J	16	1	TBD	Call TI	Level-NC-NC-NC
SNJ54LS592W	ACTIVE	CFP	W	16	1	TBD	Call TI	Level-NC-NC-NC
SNJ54LS592W	ACTIVE	CFP	W	16	1	TBD	Call TI	Level-NC-NC-NC
SNJ54LS593FK	ACTIVE	LCCC	FK	20	1	TBD	Call TI	Level-NC-NC-NC
SNJ54LS593FK	ACTIVE	LCCC	FK	20	1	TBD	Call TI	Level-NC-NC-NC
SNJ54LS593J	ACTIVE	CDIP	J	20	1	TBD	Call TI	Level-NC-NC-NC
SNJ54LS593J	ACTIVE	CDIP	J	20	1	TBD	Call TI	Level-NC-NC-NC
SNJ54LS593W	OBSOLETE			20		TBD	Call TI	Call TI
SNJ54LS593W	OBSOLETE			20		TBD	Call TI	Call TI

(1) The marketing status values are defined as follows: **ACTIVE:** Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.



PACKAGE OPTION ADDENDUM

26-Sep-2005

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS) or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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14 LEADS SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package is hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
- E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

W (R-GDFP-F16)

CERAMIC DUAL FLATPACK



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only.
- E. Falls within MIL STD 1835 GDFP1-F16 and JEDEC MO-092AC



FK (S-CQCC-N**)

28 TERMINAL SHOWN

LEADLESS CERAMIC CHIP CARRIER



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a metal lid.
- D. The terminals are gold plated.
- E. Falls within JEDEC MS-004



N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- The 20 pin end lead shoulder width is a vendor option, either half or full width.



DW (R-PDSO-G20)

PLASTIC SMALL-OUTLINE PACKAGE

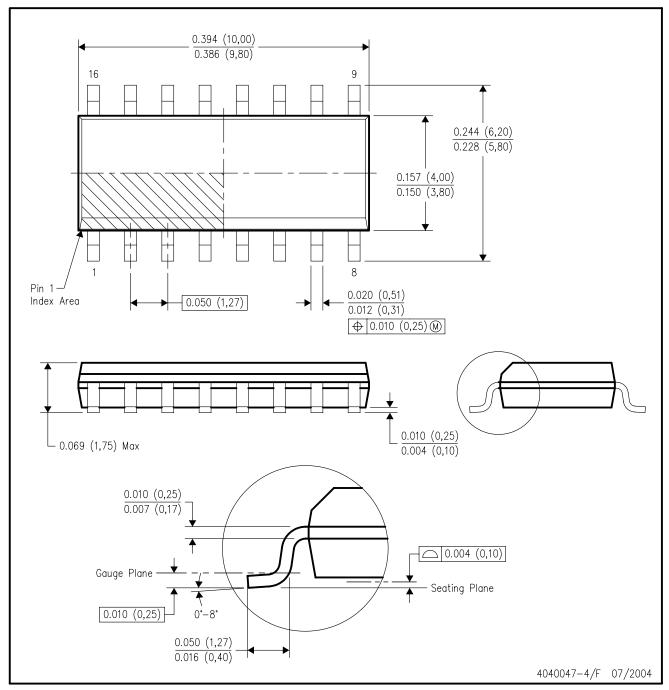


- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
- D. Falls within JEDEC MS-013 variation AC.



D (R-PDSO-G16)

PLASTIC SMALL-OUTLINE PACKAGE



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
- D. Falls within JEDEC MS-012 variation AC.



MECHANICAL DATA

NS (R-PDSO-G**)

14-PINS SHOWN

PLASTIC SMALL-OUTLINE PACKAGE



- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



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